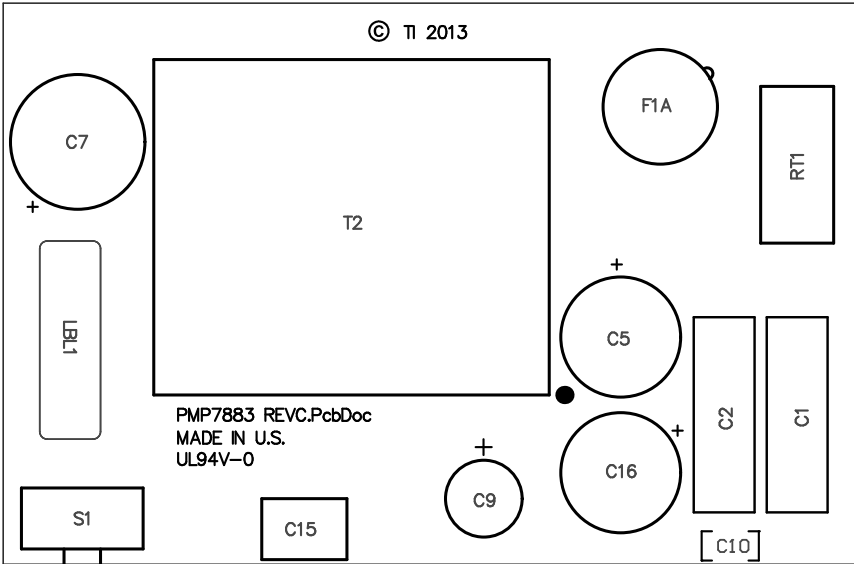


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	PROJECT NAME = PMP7883 REVC	
LAYER NAME = Top Overlay	ARTWORK # = 880 .prj_BasePN - .PCB_CAD Rev	TEXAS INSTRUMENTS
PLOT NAME = Top Assembly Drawing	GENERATED : 3/4/2013	12:32:59 PM



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS

ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	PROJECT NAME = PMP7883 REVC		
LAYER NAME =	ARTWORK # = 088 880 .prj_BasePN - .PCB_Copper_Rev	TECHNICAL COMMENTS	
PLOT NAME = Bottom Assembly Drawing		GENERATED : 3/4/2013	12:32:59 PM

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